HIGH TEMPERATURE ANTI-DROOP END EFFECTOR FOR SUBSTRATE TRANSFER

ABSTRACT

Embodiments of the present invention relates to high temperature anti-droop end effectors for transferring semiconductor substrates. One embodiment of the present invention provides an end effector for using with a substrate handler. The end effector comprises a free end having a substrate supporting plane configured to support a substrate and positioned that substrate at a first angle relative to a horizontal plane. The end effector comprises a fixed end configured to be mounted to the substrate handler, wherein the end effector is mounted to the substrate handler at a position that the substrate supporting plane is at a second angle relative to the horizontal plane when no substrate is disposed on the free end, and the first angle is different from the second angle.

(Fig. 4)